

L Number	Hits	Search Text	DB	Time stamp
1	0	modified adj chip adj attach adj process	USPAT	2004/11/03 10:58
2	1362	chip and die and package and solder and temperature and epoxy and reflow	USPAT	2004/11/03 11:00
3	121	chip and die and package and solder and temperature and epoxy and reflow and flux and residue	USPAT	2004/11/03 11:00
4	0	(chip and die and package and solder and temperature and epoxy and reflow and flux and residue) and (first adj temperature) and (second adj temperature) and time and heat and cure	USPAT	2004/11/03 11:01
5	1	(chip and die and package and solder and temperature and epoxy and reflow and flux and residue) and (first adj temperature) and (second adj temperature)	USPAT	2004/11/03 11:07
6	1	((chip and die and package and solder and temperature and epoxy and reflow and flux and residue) and (first adj temperature) and (second adj temperature) ) and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess)	USPAT	2004/11/03 11:15
7	1		USPAT	2004/11/03 11:12
8	1		USPAT	2004/11/03 11:13
9	1		USPAT	2004/11/03 11:13
10	1		USPAT	2004/11/03 11:13
11	1		USPAT	2004/11/03 11:13
12	1		USPAT	2004/11/03 11:13
13	1		USPAT	2004/11/03 11:13
14	1		USPAT	2004/11/03 11:14
15	1		USPAT	2004/11/03 11:14
16	1		USPAT	2004/11/03 11:14
17	1		USPAT	2004/11/03 11:14
18	1		USPAT	2004/11/03 11:14
19	1		USPAT	2004/11/03 11:14
20	1		USPAT	2004/11/03 11:15
21	1	"5840417".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess)	USPAT	2004/11/03 11:15
22	1	"5872051".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess)	USPAT	2004/11/03 11:16
23	1	"6169022".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:17
24	1	"6228678".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:18
25	1	"6228678".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:18

26	1	"6228681".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:20
27	1	"6238599".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:20
28	1	"6258627".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:21
29	1	"6333206".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:22
30	1	"6333209".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:23
31	1	"6372547".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:23
32	1	"6387795".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:24
33	1	"6489180".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:25
34	1	"6518093".PN. and (epoxy or cure or heat or heated or overmolding or die or chip or package or cooling or substrate or space or reflow or solder or ball or temprature or uderfilling or contact or time or sufficient or solidify or flux or residue or without or adding or excess or first or second)	USPAT	2004/11/03 11:26
35	843	438/48	USPAT	2004/11/03 11:26
36	526	438/51	USPAT	2004/11/03 11:26
37	304	438/55	USPAT	2004/11/03 11:26
38	491	438/64	USPAT	2004/11/03 11:26
39	2679	438/106	USPAT	2004/11/03 11:26
40	1894	438/108	USPAT	2004/11/03 11:26
41	1960	438/118	USPAT	2004/11/03 11:26
42	660	438/119	USPAT	2004/11/03 11:26
43	848	438/121	USPAT	2004/11/03 11:26
44	0	438/1212	USPAT	2004/11/03 11:27
45	851	438/122	USPAT	2004/11/03 11:27
46	1150	438/124	USPAT	2004/11/03 11:27
47	1202	438/126	USPAT	2004/11/03 11:27
48	1362	438/125	USPAT	2004/11/03 11:27
49	1560	438/127	USPAT	2004/11/03 11:27

11/3/04